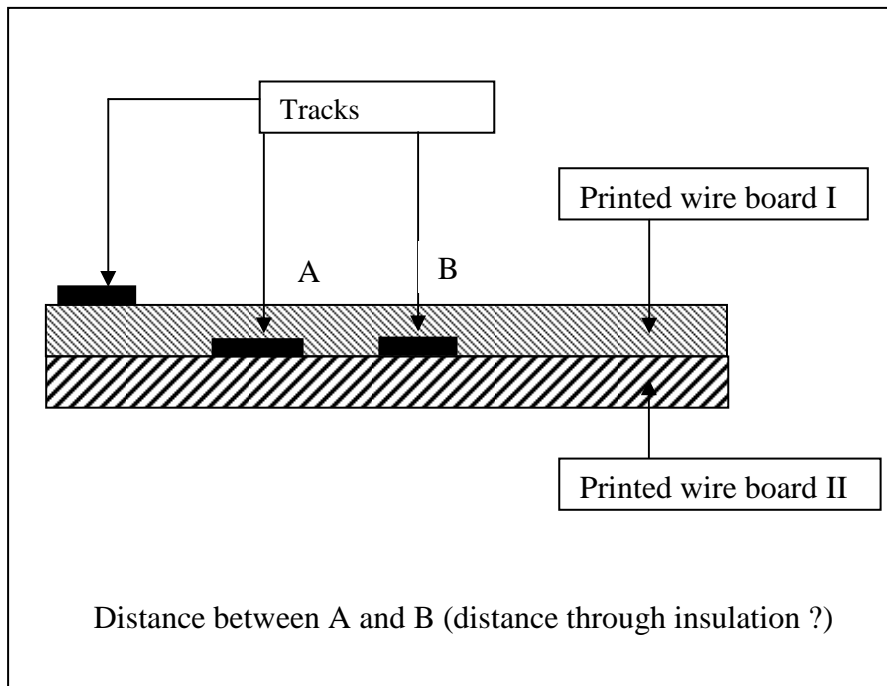


## OSM/IN DECISION

<b>Standard:</b> EN 60669-2-1:2004	<b>Sub clause:</b> 23	<b>Sheet N°:</b> OSM/IN 216
<b>Subject:</b> Electronic switch multi-layer printed wire board creepage and clearance distances	<b>Key words:</b> <ul style="list-style-type: none"> <li>- Multi-layer printed wire board</li> <li>- Creepage</li> <li>- Clearances</li> </ul>	<b>Meeting N°:</b> 14 - 17 - 18  <b>Item:</b> 6.12 - 3.4.4 - 3.4.4.3

**Question:**

What is the creepage distance between printed wire conductor on multi layer printed wire board material?



**Decision:**

The opinion of CLC/TC 23B on the matter is that there is no air gap between PCB tracks A and B of the figure above. The space between the two tracks has to be considered as solid insulation.

**Explanatory notes:**

Item discussed by CLC/TC 23B during its June 2005 general meeting in Palermo.